

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0545481271

Status:

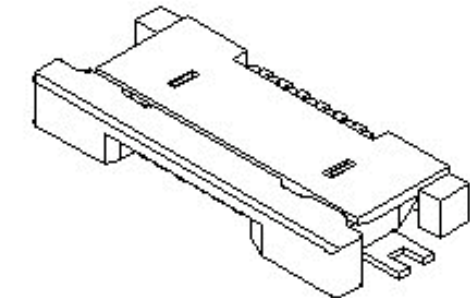
Active

Overview:

ffc_fpc_smt

Description:

0.50mm (.020") Pitch FFC/FPC Connector, 1.20mm (.047") Height, Right Angle, SMT, ZIF, Bottom Contact Style, 12 Circuits, Lead-free, Gold Contact Plating



Series

image - Reference only

Documents:

- [3D Model](#)
- [Drawing \(PDF\)](#)
- [Product Specification PS-54548-039 \(PDF\)](#)
- [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	FFC/FPC Connectors
Series	54548
Overview	ffc_fpc_smt
Product Name	N/A

Physical

Circuits (Loaded)	12
Contact Position	Bottom
Durability (mating cycles max)	20
Entry Angle	90° Angle
Mated Height (in)	0.047 In
Mated Height (mm)	1.20 mm
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Number of Rows	1
Orientation	Right Angle
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.020 In
Pitch - Mating Interface (mm)	0.50 mm
Polarized to PCB	Yes
Stackable	No
Temperature Range - Operating	-20°C to +85°C
Termination Interface: Style	Surface Mount
Wire/Cable Type	FFC/FPC

Electrical

Current - Maximum per Contact	0.5A
Voltage - Maximum	50V

Material Info

Reference - Drawing Numbers

Packaging Specification	SPK-54548-001
Product Specification	PS-54548-039, RPS-54548-083, RPS-54548-085, RPS-54548-091, RPS-54548-097, RPS-54548-099
Sales Drawing	SD-54548-039, SD-54548-040

EU RoHS

ELV and RoHS
Compliant

REACH SVHC

Not Reviewed
Halogen-Free
Status

Not Reviewed

Need more information on product
environmental compliance?

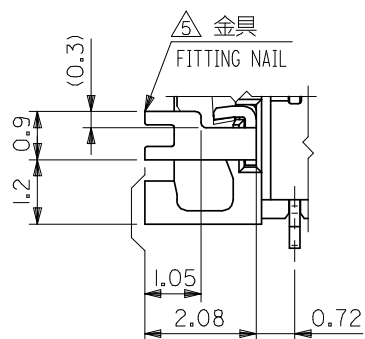
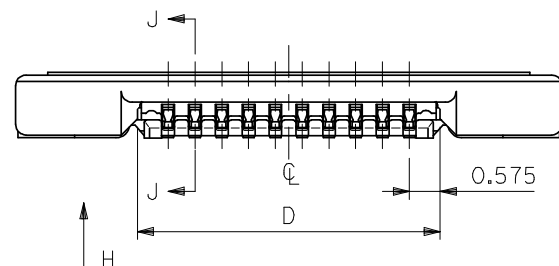
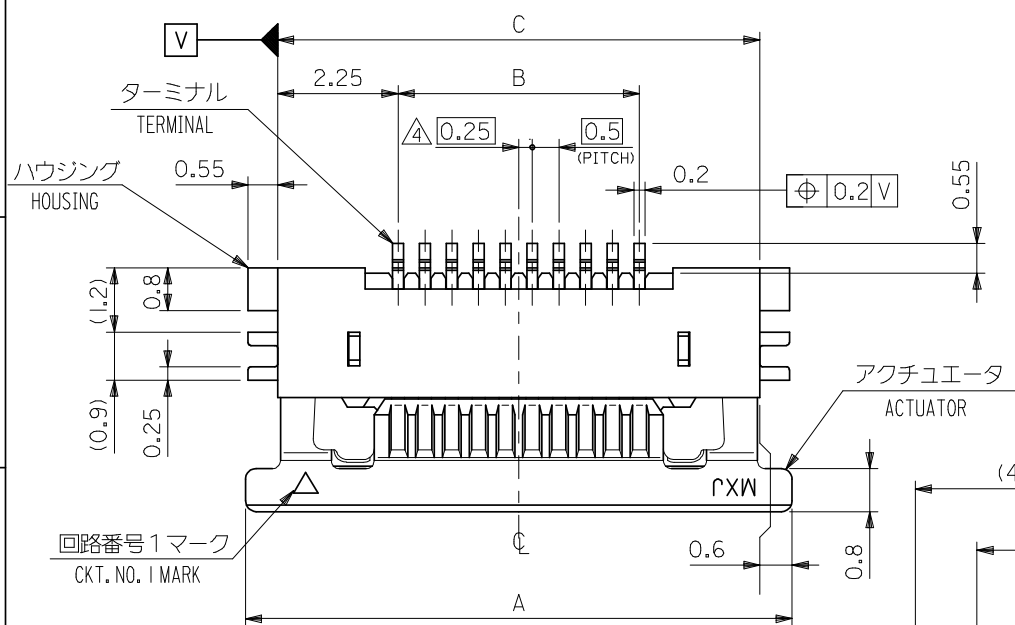
Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

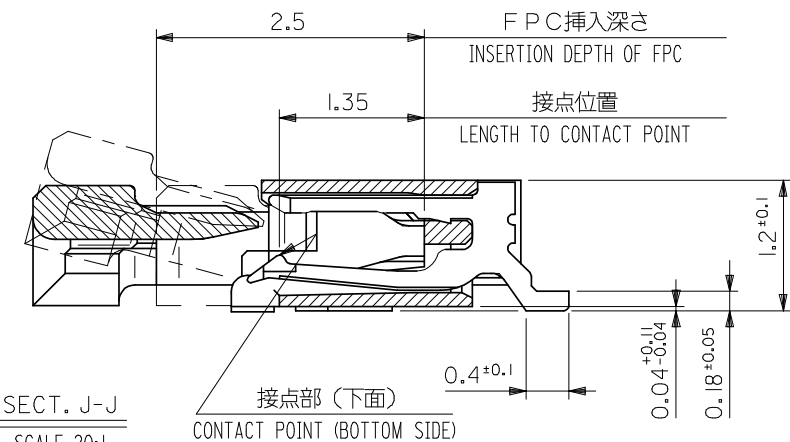
China RoHS



Search Parts in this Series
54548Series



VIEW H



SECT. J-J
SCALE 20:1

0.28±0.03	13.65	17.0	12.5	18.2	54548-2671	54548-2629	26
	12.65	16.0	11.5	17.2	54548-2471	54548-2429	24
0.3±0.03	12.15	15.5	11.0	16.7	54548-2371	54548-2329	23
	11.65	15.0	10.5	16.2	54548-2271	54548-2229	22
	11.15	14.5	10.0	15.7	54548-2171	54548-2129	21
	10.65	14.0	9.5	15.2	54548-2071	54548-2029	20
	10.15	13.5	9.0	14.7	54548-1971	54548-1929	19
	9.65	13.0	8.5	14.2	54548-1871	54548-1829	18
	9.15	12.5	8.0	13.7	54548-1771	54548-1729	17
	8.65	12.0	7.5	13.2	54548-1671	54548-1629	16
	8.15	11.5	7.0	12.7	54548-1571	54548-1529	15
	7.65	11.0	6.5	12.2	54548-1471	54548-1429	14
	7.15	10.5	6.0	11.7	54548-1371	54548-1329	13
	6.65	10.0	5.5	11.2	54548-1271	54548-1229	12
	6.15	9.5	5.0	10.7	54548-1171	54548-1129	11
	5.65	9.0	4.5	10.2	54548-1071	54548-1029	10
	5.15	8.5	4.0	9.7	54548-0971	54548-0929	9
	4.65	8.0	3.5	9.2	54548-0871	54548-0829	8
	4.15	7.5	3.0	8.7	54548-0771	54548-0729	7
	3.65	7.0	2.5	8.2	54548-0671	54548-0629	6
3.15	6.5	2.0	7.7	54548-0571	54548-0529	5	
2.65	6.0	1.5	7.2	54548-0471	54548-0429	4	
FPC THICKNESS	D	C	B	A	EMBOSSD TAPE ORDER No. オーダー番号	製品番号 MATERIAL No.	極数 Ck+

54548-**29	MODEL No.
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DESIGN UNITS	THIRD ANGLE
METRIC	PROJECTION

0.5 FPC CONN ZIF HSG
ASSY FOR SMT RA BTM CONT
-LEAD FREE-

 MOLEX INCORPORATED

DOCUMENT NO. SD-54548-039	SHEET NO. 1 OF 2
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THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISED	EC NO: J2008-4048	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	DRWN:WABEI		10 UNDER	± 0.2
	CH'KD: THIRUYAMA		10 OVER 30 UNDER	± 0.25
	APPR: NUKITA		30 OVER	± 0.3
			ANGULAR	± 3 °
		REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

F

E

D

C

B

A

F

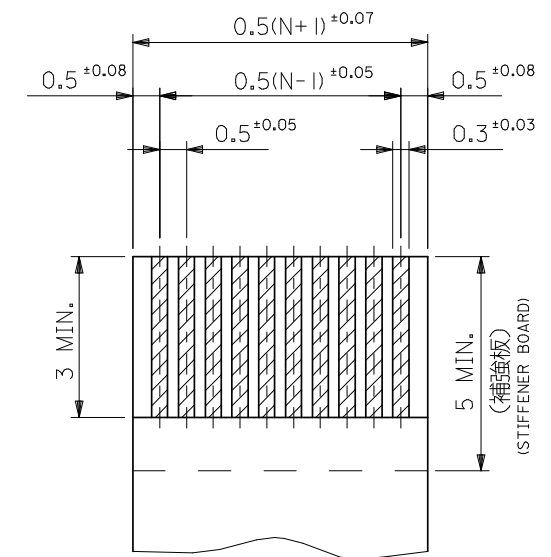
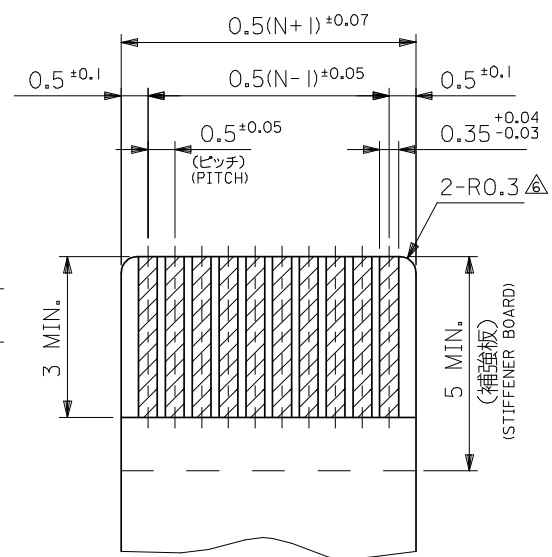
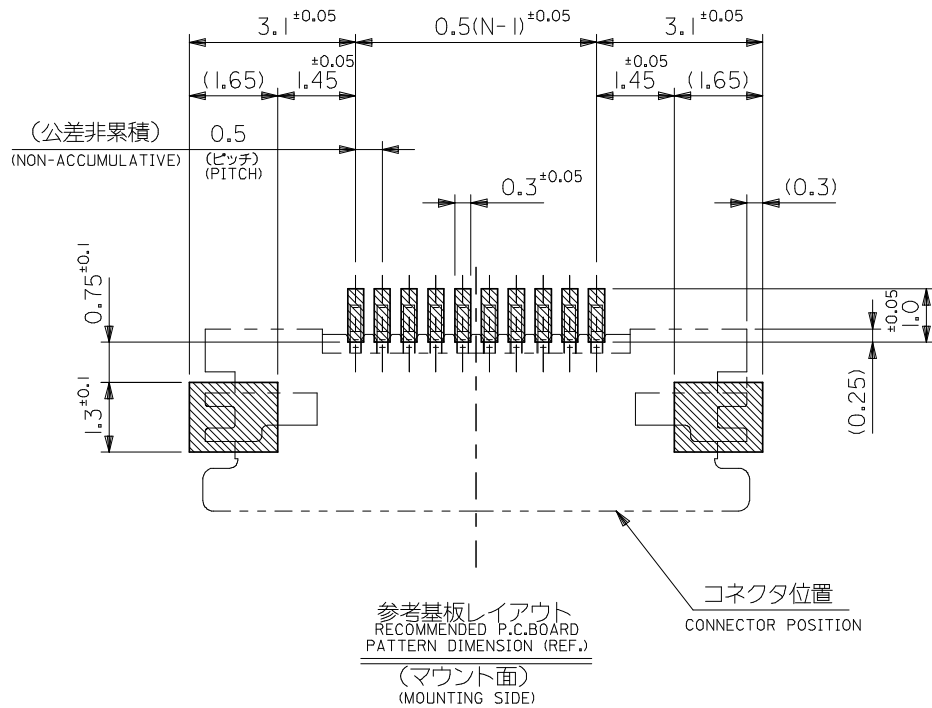
E

D

C

B

A



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 表参照)
(THICKNESS: SEE CHART)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 表参照)
(THICKNESS: SEE CHART)

注記 NOTES

I. 使用材料 MATERIAL

- ハウジング : LCP, UL94V-0
HOUSING
アクチュエータ : PPS, UL94V-0
ACTUATOR
ターミナル : リン青銅 (t=0.2)
TERMINAL PHOSPOR BRONZE
メッキ : 接点部: 金メッキ
PLATING CONTACT PORTION : GOLD PLATING
テール部: 鍍メッキ
SOLDERING PORTION : TIN OVER PLATING
下地: ニッケルメッキ
UNDER PLATING: NICKEL PLATING
金具 : リン青銅、鍍メッキ (t=0.2)
FITTING NAIL PHOSPOR BRONZE, TIN PLATING
下地: ニッケルメッキ
UNDER PLATING: NICKEL PLATING

- △ パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
△ RO.3はFPC導体部にかからないこと
RO.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
7. 本製品は54548-**-21の鉛フリー(部分金メッキ)品である。
THIS PRODUCT IS LEAD FREE OF 54548-**-21 (SELECTIVE GOLD).
8. N: 極数 N: CIRCUIT.

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54548-**-29 SHOULD BE LOCKED.
△ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 Z
に対し上方向 0 MAX.、下方向 0.15 MAX.とし
相互のバツキ量は0.1 MAX.とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM Z
UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX.
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
△ 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

FPC/FFC について:

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟銅箔35μmまたは50μmを推奨します。

ABOUT FPC/FFC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

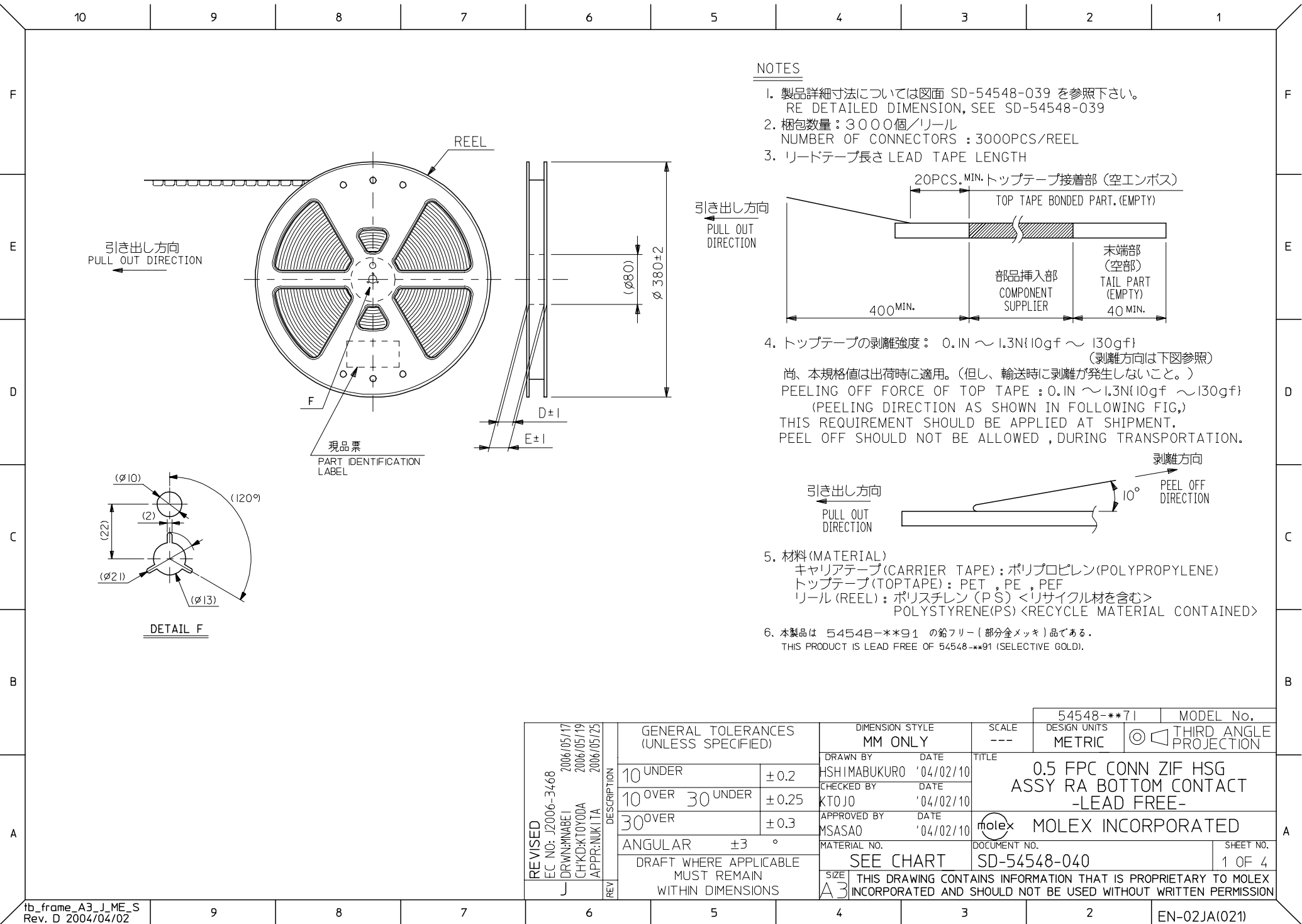
FPC について:

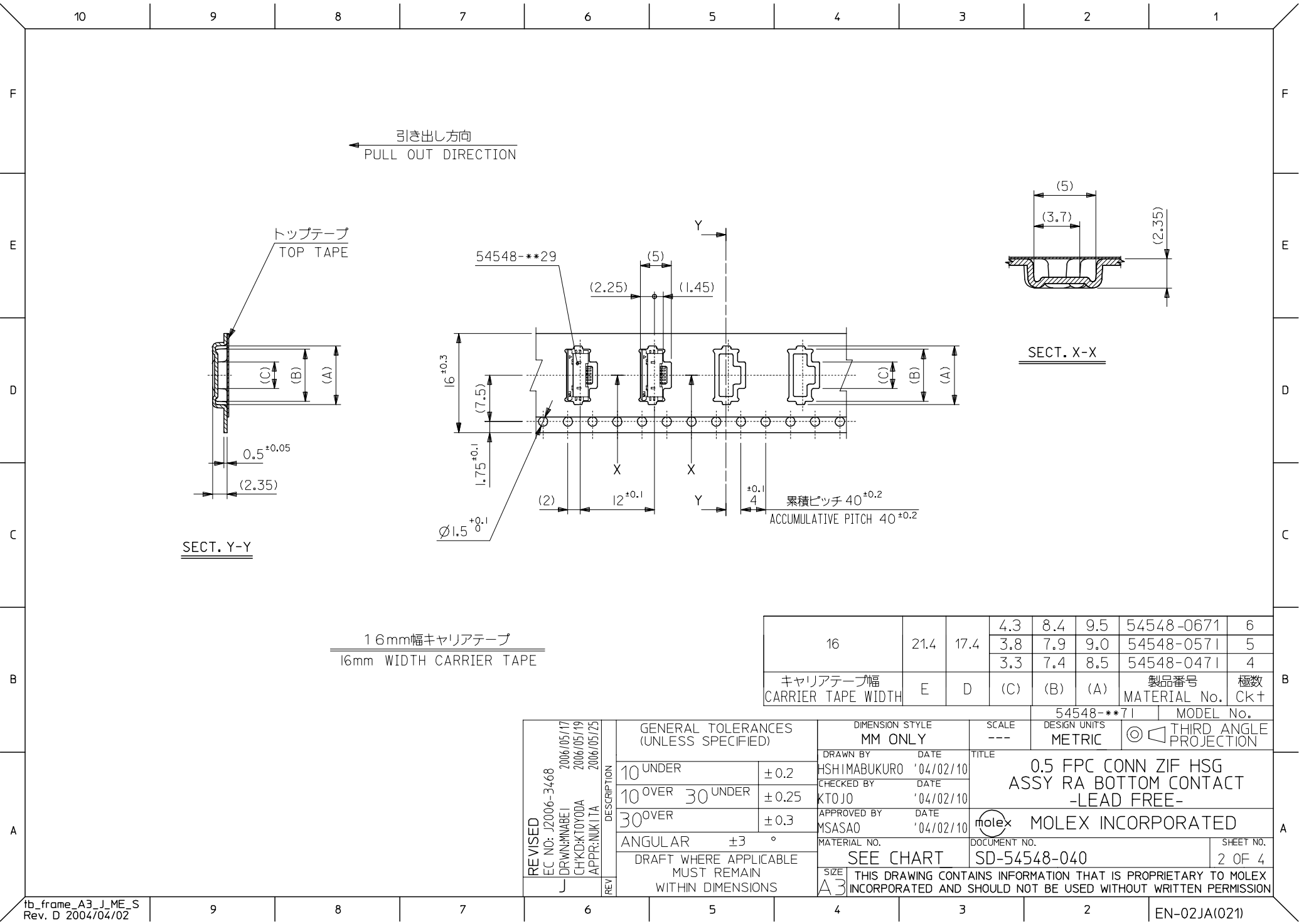
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

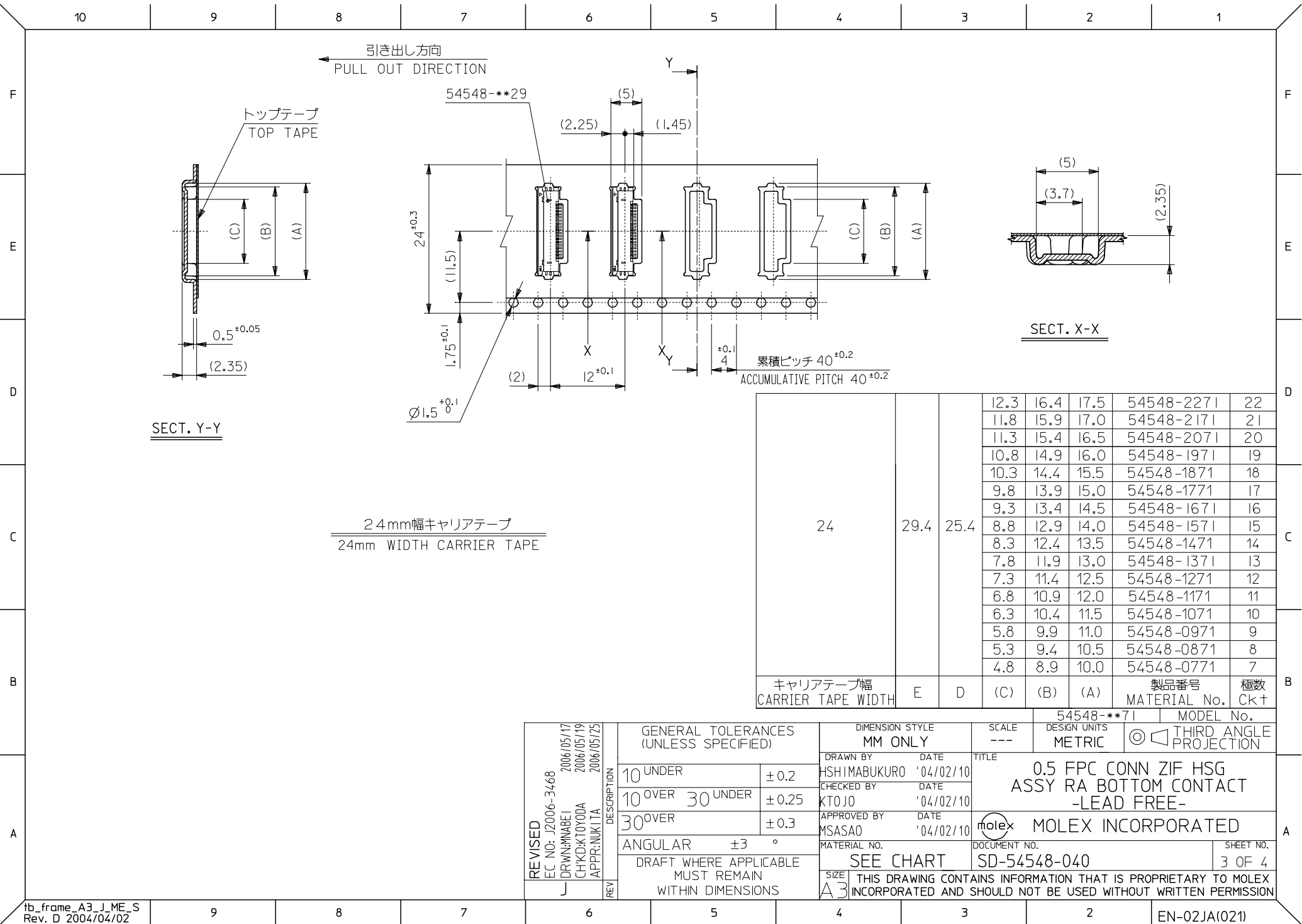
ABOUT FPC

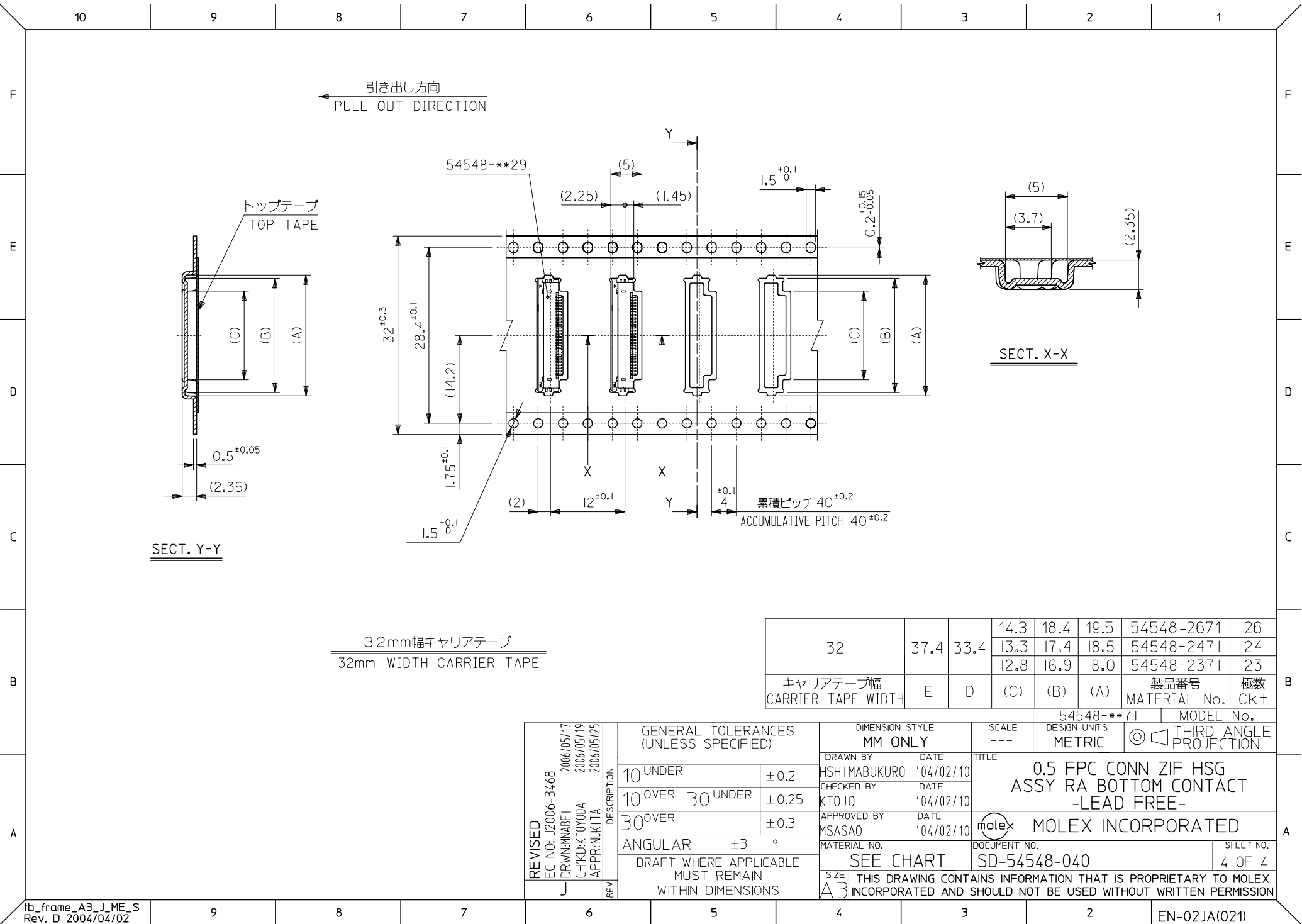
RECOMMENDED MATERIAL/THICKNESS.
STIFFENER FILM : POLYIMIDE
BASE FILM THICKNESS : 25μm
BONDING AGENT : THERMOSETTING BONDING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON THE CONTACT
AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN
ELECTRICAL CONTINUITY.

REVISED EC NO: J2008-4048 DRWN:WABEI CHKD:THARUYAMA APPR:NUKITA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	20 THIRD ANGLE PROJECTION	MODEL NO.
		10 UNDER	±0.2	DRAWN BY HSHIMABUKURO	DATE '04/02/10	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE '04/02/10				
		30 OVER	±0.3	APPROVED BY MSASAO	DATE '04/02/10	molex MOLEX INCORPORATED			
		ANGULAR	±3 °	MATERIAL NO.					
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE SHEET 1		SD-54548-039		2 OF 2		
	REV	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							









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<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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